



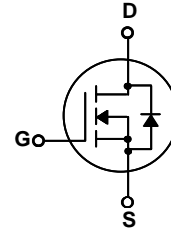
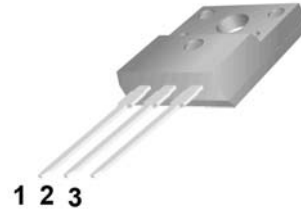
## IRF630

### 200V N-Channel MOSFET

#### Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : 22 nC (Typ.)
- BVDSS=200V, ID=9A
- Lower  $R_{DS(on)}$  : 0.4  $\Omega$  (Max) @VG=10V
- 100% Avalanche Tested

TO-220F



G-Gate, D-Drain, S-Source

#### **Absolute Maximum Ratings** $T_c=25^\circ\text{C}$ unless other wise noted

Symbol	Parameter	WGF630	Units
$V_{DSS}$	Drain-Source Voltage	200	V
$I_D$	Drain Current -continuous ( $T_c=25^\circ\text{C}$ )	9	A
	-continuous ( $T_c=100^\circ\text{C}$ )	5.7	A
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avanche Energy (Note1)	160	mJ
$I_{AR}$	Avalanche Current (Note2)	9	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	72	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 ~ +150	$^\circ\text{C}$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

#### Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	--	1.74	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case to Sink	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	--	62.5	$^\circ\text{C}/\text{W}$

<b>Electrical Characteristics</b> Tc=25°C unless other wise noted						
Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	ID=250 μ A, VGS=0	200	--	--	V
Δ BV <sub>DSS</sub> / Δ T <sub>J</sub>	Breakdown Voltage Temperature Coefficient	ID=250 μ A, Reference to 25°C	--	0.2	--	V/°C
IDSS	Zero Gate Voltage Drain Current	Vds=200V, Vgs=0V	--	--	1	μ A
		Vds=160V, Tc=125°C			10	μ A
IGSSF	Gate-body leakage Current, Forward	Vgs=+30V, Vds=0V	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	Vgs=-30V, Vds=0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	Id=250uA, Vds=Vgs	2	--	4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	Id=5A, Vgs=10V	--	--	0.4	Ω
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	550	720	pF
Coss	Output Capacitance		--	85	110	pF
Crss	Reverse Transfer Capacitance		--	22	29	pF
<b>Switching Characteristics</b>						
Td(on)	Turn-On Delay Time	VDD=100V, ID=9A, RG=25 Ω (Note 3,4)	--	11	25	nS
Tr	Turn-On Rise Time		--	70	140	nS
Td(off)	Turn-Off Delay Time		--	60	120	nS
Tf	Turn-Off Fall Time		--	65	130	nS
Qg	Total Gate Charge	VDS=160, VGS=10V, ID=9A (Note 3,4)	--	22	30	nC
Qgs	Gate-Source Charge		--	4.0	--	nC
Qgd	Gate-Drain Charge		--	11	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	9	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	36	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	Id=9A	--	--	1.5	V
trr	Reverse Recovery Time	I <sub>S</sub> =9.0A, V <sub>GS</sub> =0V	--	140	--	nS
Qrr	Reverse Recovery Charge	di <sub>F</sub> /dt=100A/ μ s (Note3)	--	0.87	--	μ C
*Notes	1, L=3.0mH, IAS=9.0A, VDD=50V, RG=25Ω, Starting T <sub>J</sub> =25°C 2, Repetitive Rating : Pulse width limited by maximum junction temperature 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2% 4, Essentially Independent of Operating Temperature					

# Typical Characteristics

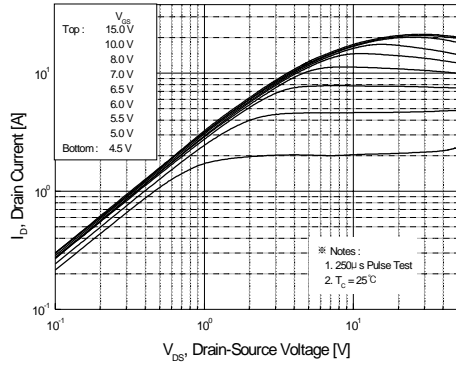


Figure 1. On-Region Characteristics

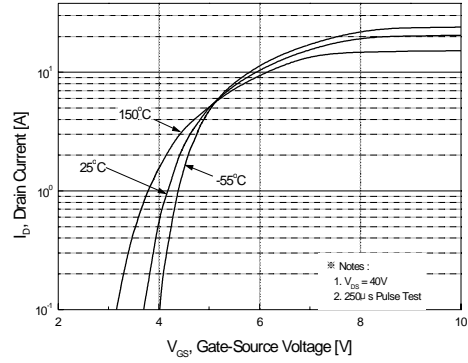


Figure 2. Transfer Characteristics

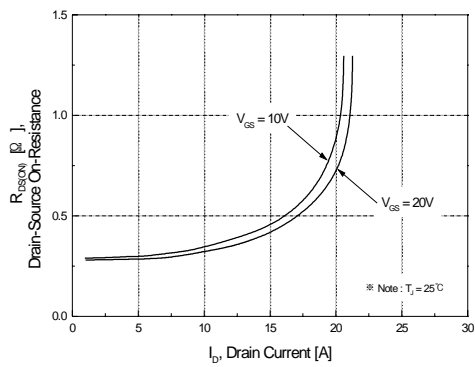


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

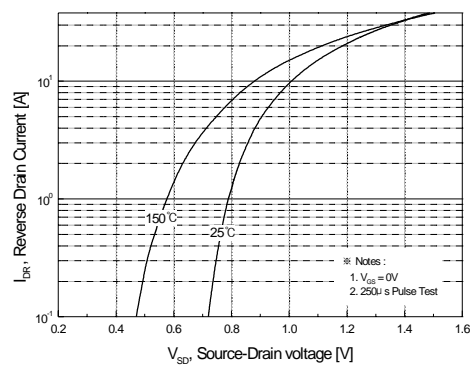


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

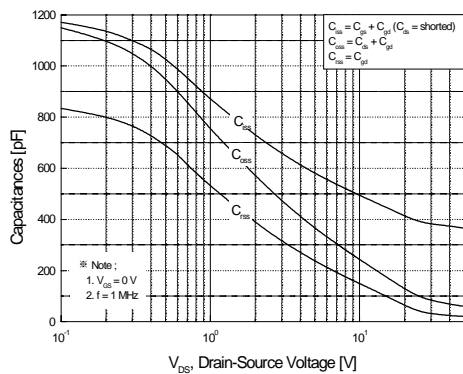


Figure 5. Capacitance Characteristics

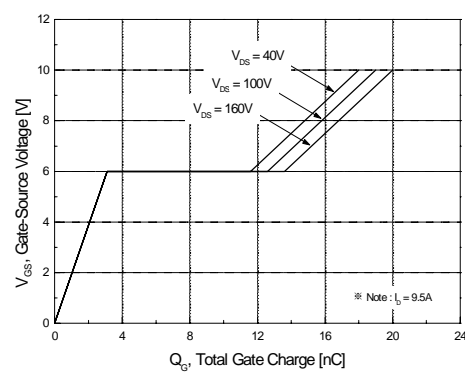


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

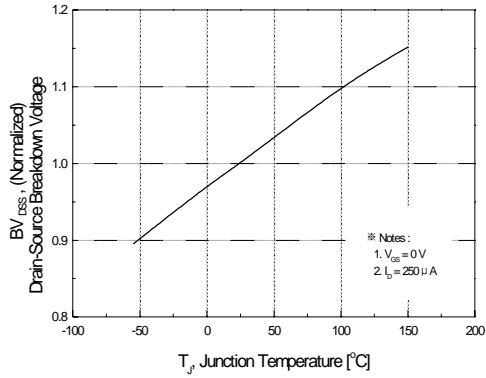


Figure 7. Breakdown Voltage Variation vs Temperature

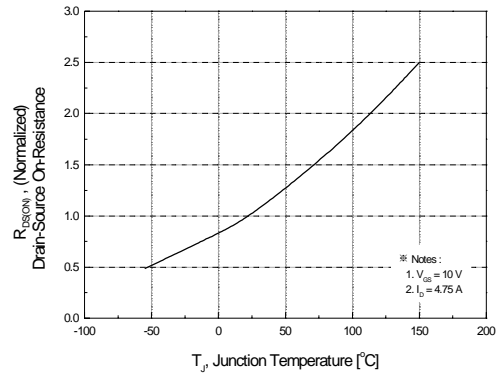


Figure 8. On-Resistance Variation vs Temperature

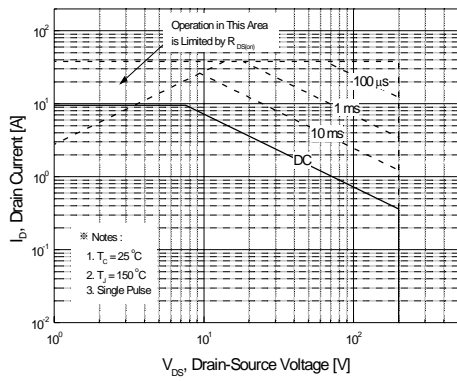


Figure 9-1. Maximum Safe Operating Area

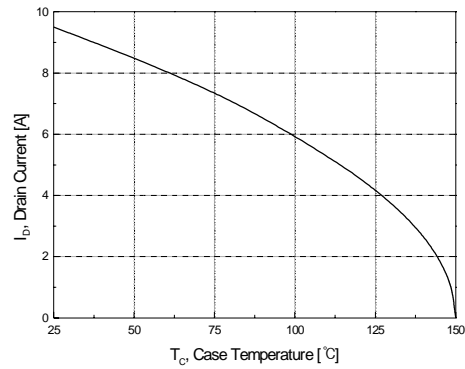


Figure 10. Maximum Drain Current vs Case Temperature

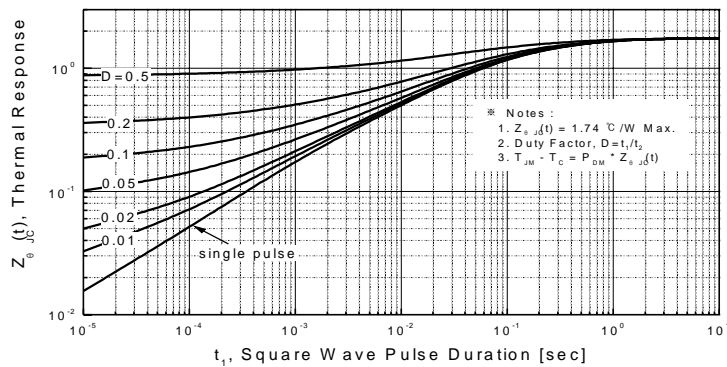
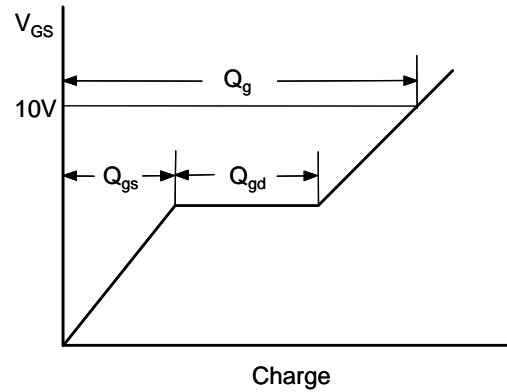
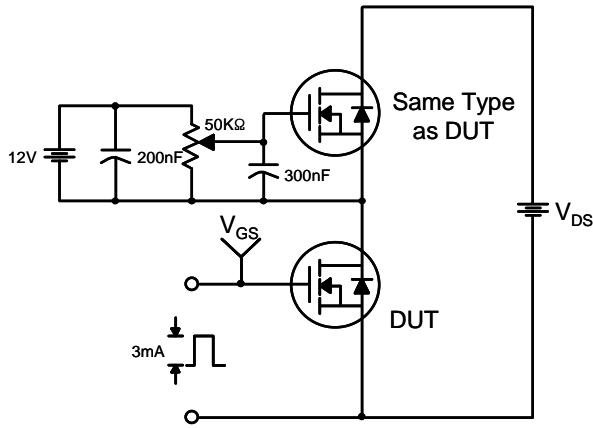
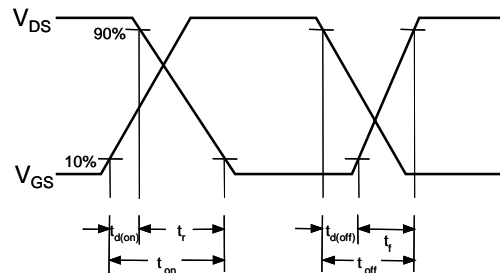
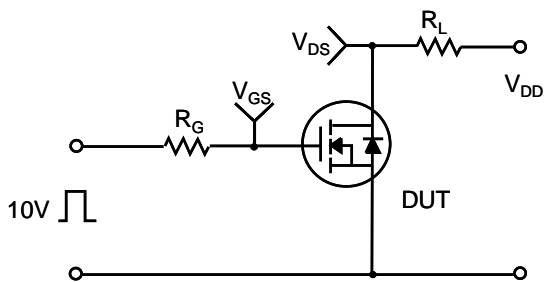


Figure 11-1. Transient Thermal Response Curve

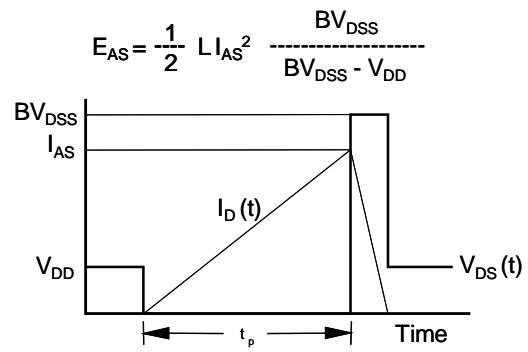
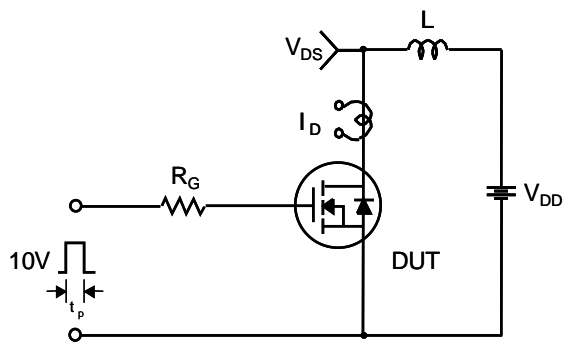
Gate Charge Test Circuit & Waveform



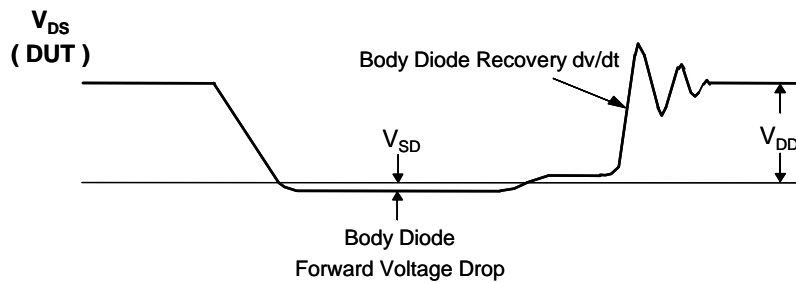
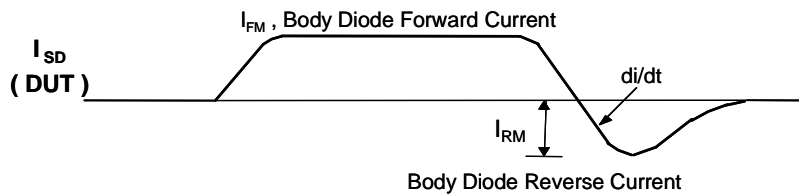
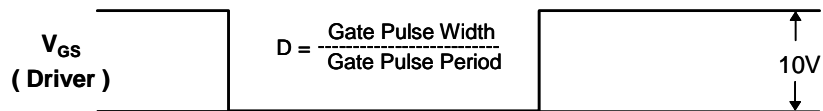
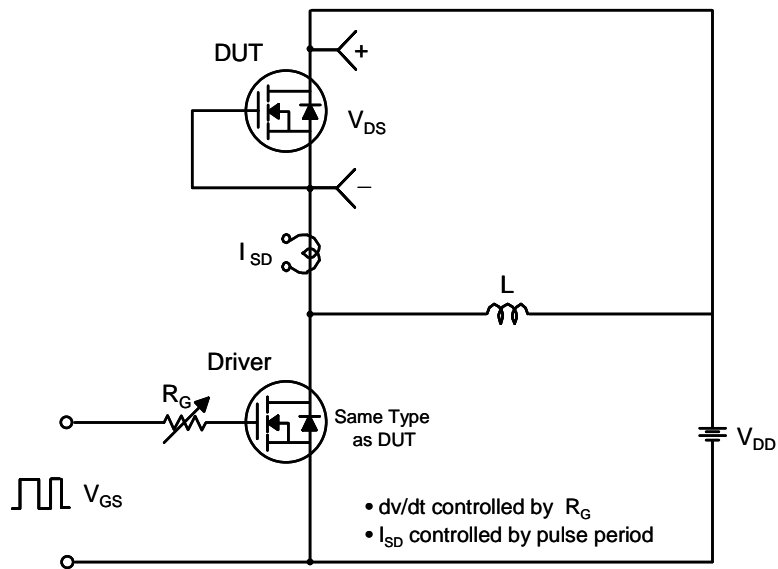
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



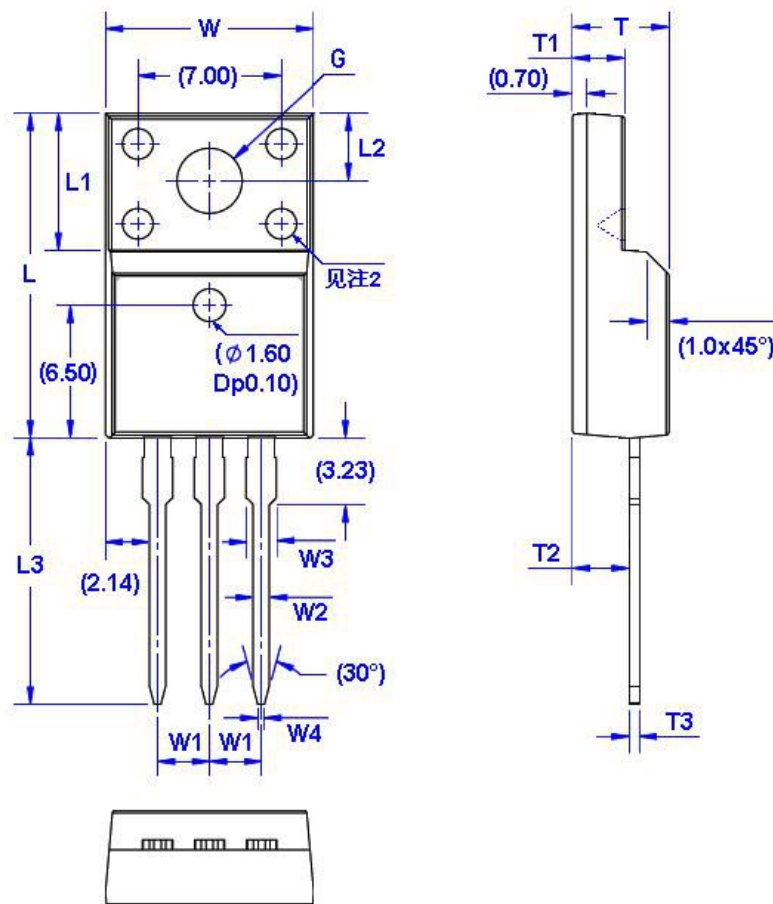
Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension

TO-220F

Unit: mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.96	10.36	W4	0.25	0.45	L3	12.78	13.18	T3	0.45	0.60
W1	2.54 (TYP)		L	15.67	16.07	T	4.50	4.90	G( $\Phi$ )	3.08	3.28
W2	0.70	0.90	L1	6.48	6.88	T1	2.34	2.74			
W3	1.24	1.47	L2	3.20	3.40	T2	2.56	2.96			